54F164A

54F164A Serial-In, Parallel-Out Shift Register

Literature Number: SNOS160

National Semiconductor

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54F/74F164A
Serial-In, Parallel-Out Shift Register

General Description

The 'F164A is a high-speed 8-bit serial-in/parallel-out shift register. Serial data is entered through a 2-input AND gate synchronous with the LOW-to-HIGH transition of the clock. The device features an asynchronous Master Reset which clears the register, setting all outputs LOW independent of the clock. The 'F164A is a faster version of the 'F164.

Features

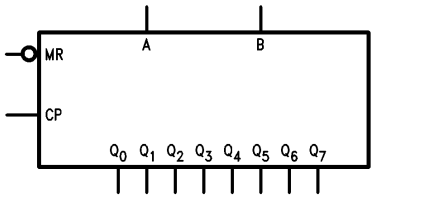
- Typical shift frequency of 90 MHz
- Asynchronous Master Reset
- Gated serial data input
- Fully synchronous data transfers
- Guaranteed 4000V min ESD protection
- 'F164A is a faster version of the 'F164

Commercial	Military	Package Number	Package Description
74F164APC		N14A	14-Lead (0.300″ Wide) Molded Dual-In-Line
	54F164ADM (Note 2)	J14A	14-Lead Ceramic Dual-In-Line
74F164ASC (Note 1)		M14A	14-Lead (0.150″ Wide) Molded Small Outline, JEDEC
74F164ASJ (Note 1)		M14D	14-Lead (0.300″ Wide) Molded Small Outline, EIAJ
	74F164AFM (Note 2)	W14B	14-Lead Cerpack
	74F164ALM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

Note 1: Devices also available in 13″ reel. Use suffix = SCX and SJX.

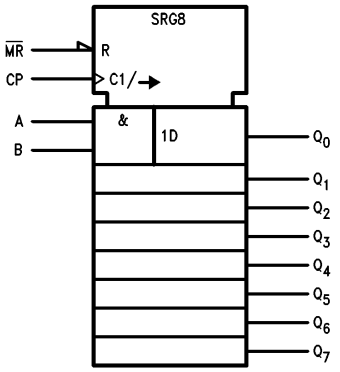
Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMQB, FMQB and LMQB.

Logic Symbols



TL/F/10613–1

IEEE/IEC



TL/F/10613–4

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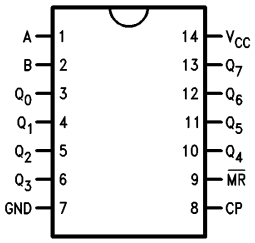
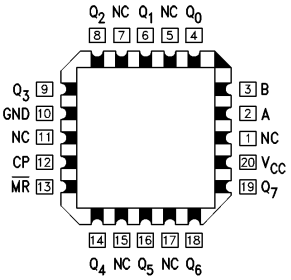
Connection Diagrams

Pin Assignment for DIP, SOIC and Flatpak



TL/F/10613–2

Pin Assignment for LCC



TL/F/10613–3

Unit Loading/Fan Out

Pin Names	Description	54F/74F	
		U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
A, B	Data Inputs	1.0/1.0	20 μA/ −0.6 mA
CP	Clock Pulse Input (Active Rising Edge)	1.0/1.0	20 μA/ −0.6 mA
$\overline{MR}$	Master Reset Input (Active LOW)	1.0/1.0	20 μA/ −0.6 mA
Q_0–Q_7	Outputs	50/33.3	−1 mA/20 mA

Functional Description

The ’F164A is an edge-triggered 8-bit shift register with serial data entry and an output from each of the eight stages. Data is entered serially through one of two inputs (A or B); either of these inputs can be used as an active HIGH Enable for data entry through the other input. An unused input must be tied HIGH.

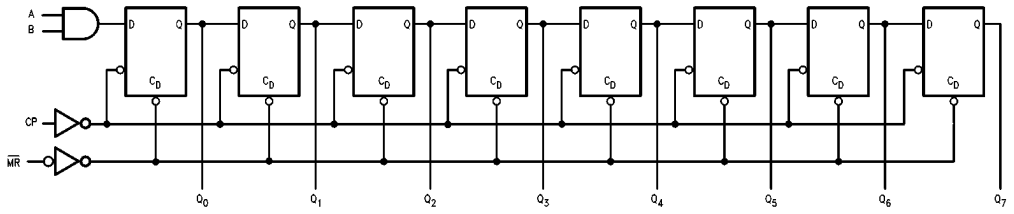
Each LOW-to-HIGH transition on the Clock (CP) input shifts data one place to the right and enters into Q_0 the logical AND of the two data inputs (A • B) that existed before the rising clock edge. A LOW level on the Master Reset ($\overline{MR}$) input overrides all other inputs and clears the register asynchronously, forcing all Q outputs LOW.

Mode Select Table

Operating Mode	Inputs			Outputs	
	$\overline{MR}$	A	B	Q_0	Q_1–Q_7
Reset (Clear)	L	X	X	L	L-L
Shift	H	l	l	L	q_0–q_6
	H	l	h	L	q_0–q_6
	H	h	l	L	q_0–q_6
	H	h	h	H	q_0–q_6

H(h) = HIGH Voltage Levels
L(l) = LOW Voltage Levels
X = Immaterial
q_n = Lower case letters indicate the state of the referenced input or output one setup time prior to the LOW-to-HIGH clock transition.

Logic Diagram



TL/F/10613–5

Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +175°C
Plastic	−55°C to +150°C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V_{CC} = 0V)	
Standard Output	−0.5V to V_{CC}
TRI-STATE® Output	−0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I_{OL} (mA)
ESD Last Passing Voltage (Min)	4000V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature	
Military	−55°C to +125°C
Commercial	0°C to +70°C
Supply Voltage	
Military	+4.5V to +5.5V
Commercial	+4.5V to +5.5V

DC Electrical Characteristics

Symbol	Parameter		54F/74F Min	54F/74F Typ	54F/74F Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal
V_{CD}	Input Clamp Diode Voltage				−1.2	V	Min	I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage	54F 10% V_{CC}	2.5			V	Min	I_{OH} = −1 mA
		74F 10% V_{CC}	2.5					I_{OH} = −1 mA
		74F 5% V_{CC}	2.7					I_{OH} = −1 mA
V_{OL}	Output LOW Voltage	54F 10% V_{CC}			0.5	V	Min	I_{OL} = 20 mA
		74F 10% V_{CC}			0.5			I_{OL} = 20 mA
I_{IH}	Input HIGH Current	54F			20.0	μA	Max	V_{IN} = 2.7V
		74F			5.0			
I_{BVI}	Input HIGH Current Breakdown Test	54F			100	μA	Max	V_{IN} = 7.0V
		74F			7.0			
I_{CEX}	Output HIGH Leakage Current	54F			250	μA	Max	V_{OUT} = V_{CC}
		74F			50			
V_{ID}	Input Leakage Test	74F	4.75			V	0.0	I_{ID} = 1.9 μA All other pins grounded
I_{OD}	Output Leakage Circuit Current	74F			3.75	μA	0.0	V_{IOD} = 150 mV All other pins grounded
I_{IL}	Input LOW Current				−0.6	mA	Max	V_{IN} = 0.5V
I_{OS}	Output Short-Circuit Current		−60		−150	mA	Max	V_{OUT} = 0V
I_{CC}	Power Supply Current			35	55	mA	Max	CP = HIGH $\overline{MR}$ = GND, A, B = GND

AC Electrical Characteristics

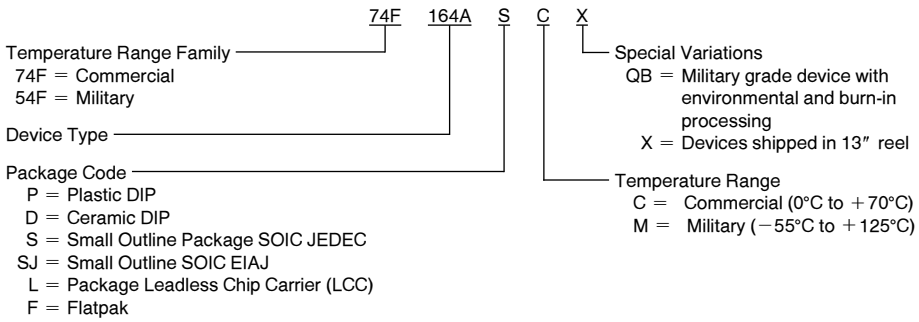
Symbol	Parameter	74F $T_A = +25°C$ $V_{CC} = +5.0V$ $C_L = 50\ pF$			54F $T_A, V_{CC} = Mil$ $C_L = 50\ pF$		74F $T_A, V_{CC} = Com$ $C_L = 50\ pF$		Units
		Min	Typ	Max	Min	Max	Min	Max	
f_{max}	Maximum Clock Frequency	80	120		60		80		MHz
t_{PLH} t_{PHL}	Propagation Delay CP to Q_n	3.0 3.5	4.8 5.0	7.5 8.0	2.5 3.0	9.0 8.5	3.0 3.5	7.5 8.0	ns
t_{PHL}	Propagation Delay $\overline{MR}$ to Q_n	5.0	7.0	10.0	4.0	12.5	5.0	10.5	ns

AC Operating Requirements

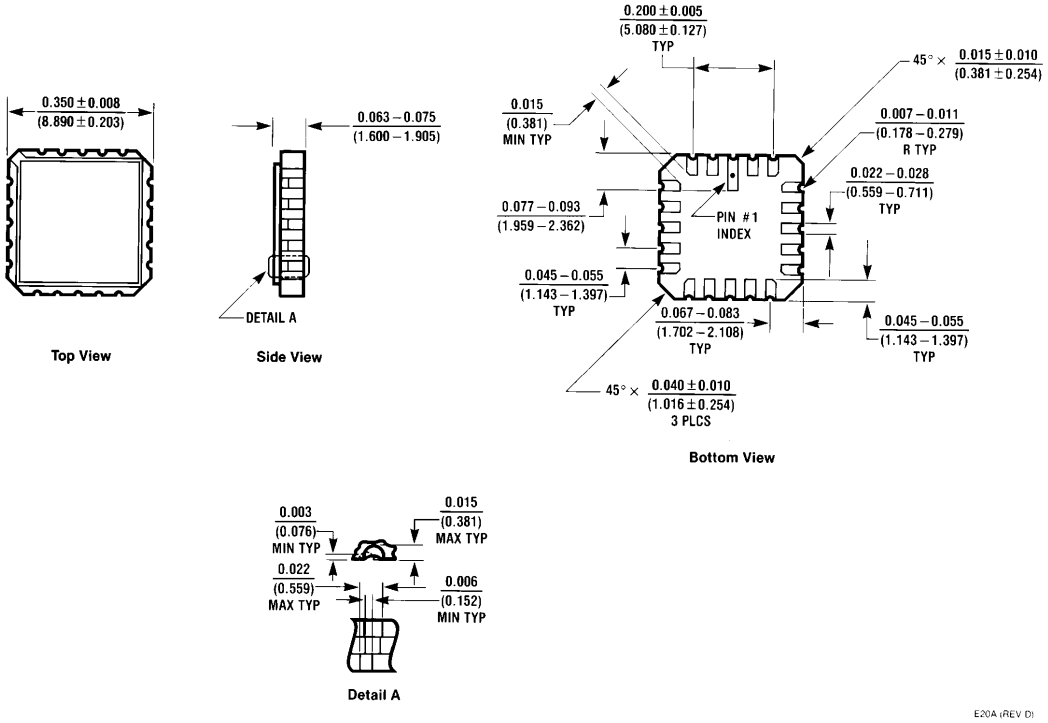
Symbol	Parameter	74F $T_A = +25°C$ $V_{CC} = +5.0V$		54F $T_A, V_{CC} = Mil$		74F $T_A, V_{CC} = Com$		Units
		Min	Max	Min	Max	Min	Max	
$t_s(H)$ $t_s(L)$	Setup Time, HIGH or LOW A or B to CP	4.5 4.0		5.5 4.0		4.5 4.0		ns
$t_h(H)$ $t_h(L)$	Hold Time, HIGH or LOW A or B to CP	1.0 1.0		1.0 1.0		1.0 1.0		
$t_w(H)$ $t_w(L)$	CP Pulse Width HIGH or LOW	4.0 7.0		4.0 7.0		4.0 7.0		ns
$t_w(L)$	$\overline{MR}$ Pulse Width, LOW	4.0		5.0		4.0		ns
t_{rec}	Recovery Time $\overline{MR}$ to CP	5.0		6.5		5.0		ns

Ordering Information

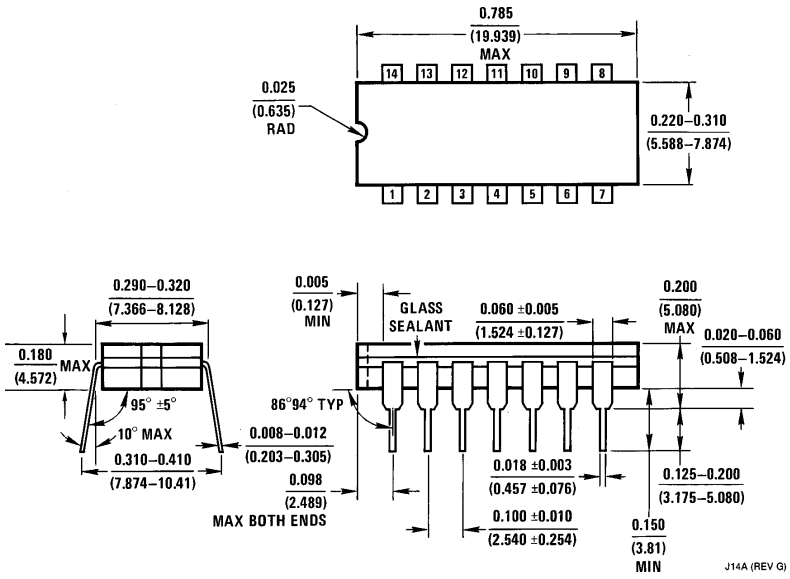
The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:



Physical Dimensions inches (millimeters)

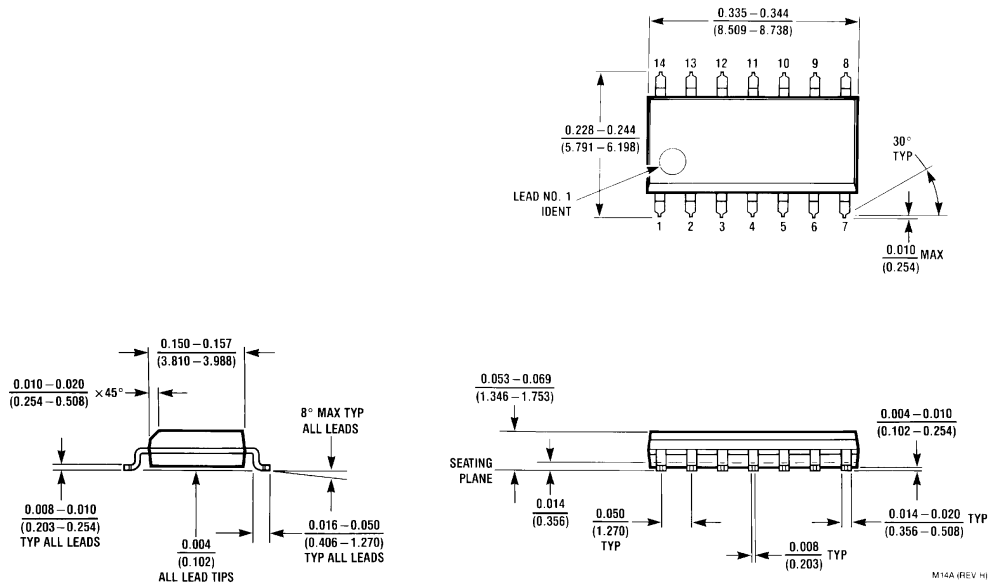


20-Lead Ceramic Leadless Chip Carrier, Type C (L)
NS Package Number E20A



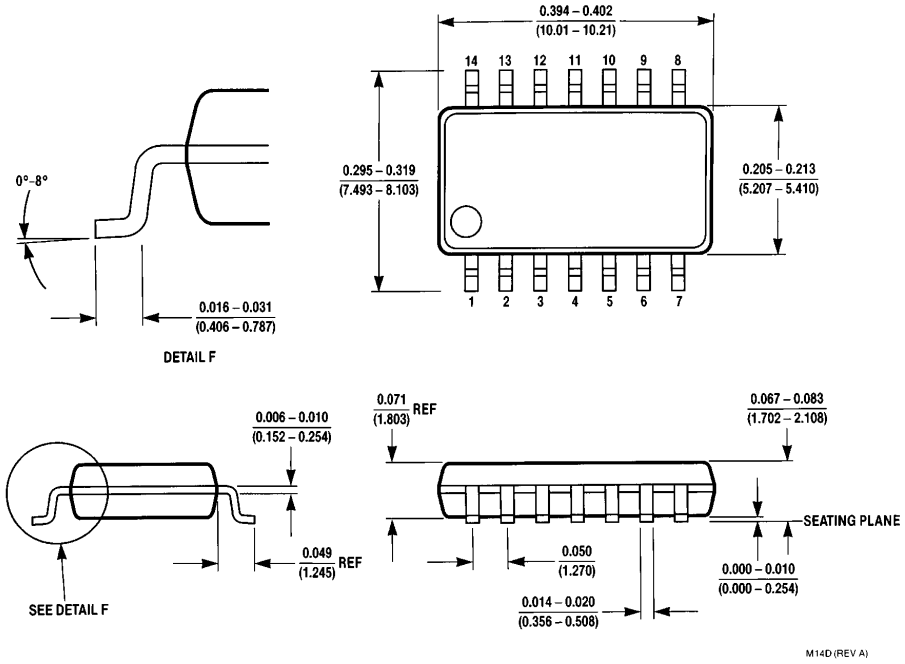
14-Lead Ceramic Dual-In-Line Package (D)
NS Package Number J14A

Physical Dimensions inches (millimeters) (Continued)

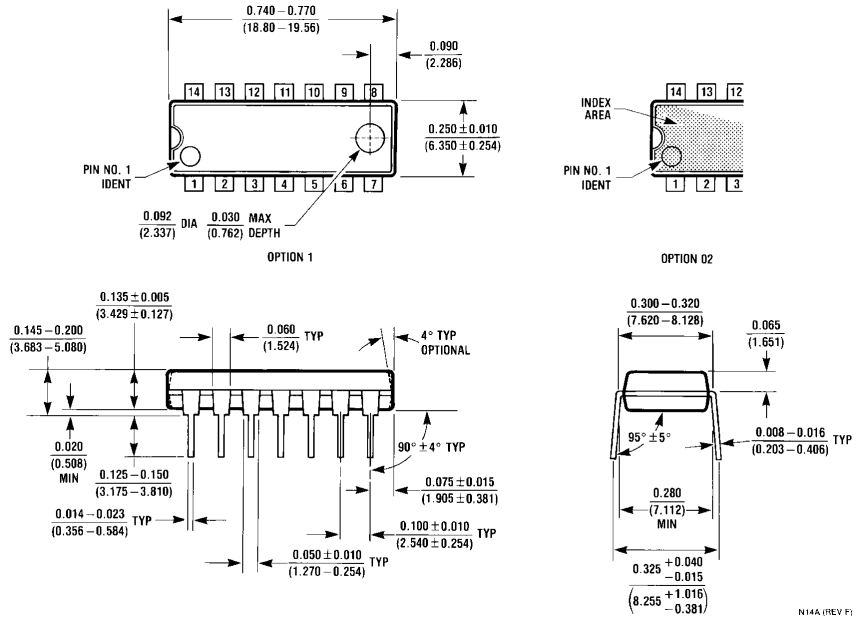


14-Lead (0.150″ Wide) Molded Small Outline Package, JEDEC (S)
NS Package Number M14A

Physical Dimensions inches (millimeters) (Continued)

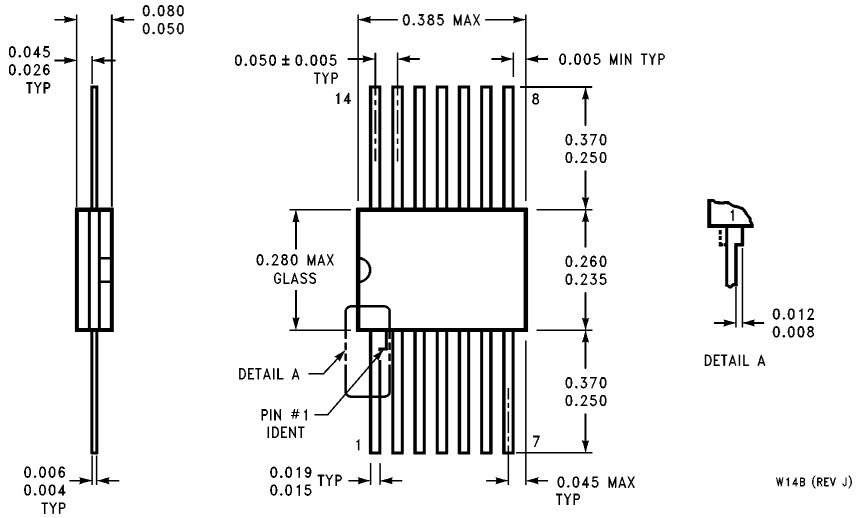


14-Lead (0.300″ Wide) Molded Small Outline Package, EIAJ (SJ)
NS Package Number M14D



14-Lead (0.300″ Wide) Plastic Dual-In-Line Package (P)
NS Package Number N14A

Physical Dimensions inches (millimeters) (Continued)



14-Lead Cerpack (F)
NS Package Number W14B

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2900 Semiconductor Drive
P.O. Box 58090
Santa Clara, CA 95052-8090
Tel: 1(800) 272-9959
TWX: (910) 339-9240

National Semiconductor GmbH
Livry-Gargan-Str. 10
D-82256 Fürstenfeldbruck
Germany
Tel: (81-41) 35-0
Telex: 527649
Fax: (81-41) 35-1

National Semiconductor Japan Ltd.
Sumitomo Chemical
Engineering Center
Bldg. 7F
1-7-1, Nakase, Mihama-Ku
Chiba-City,
Ciba Prefecture 261
Tel: (043) 299-2300
Fax: (043) 299-2500

National Semiconductor Hong Kong Ltd.
13th Floor, Straight Block,
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Tsimshatsui, Kowloon
Hong Kong
Tel: (852) 2737-1600
Fax: (852) 2736-9960

National Semiconductores Do Brazil Ltda.
Rue Deputado Lacorda Franco
120-3A
Sao Paulo-SP
Brazil 05418-000
Tel: (55-11) 212-5066
Telex: 391-1131931 NSBR BR
Fax: (55-11) 212-1181

National Semiconductor (Australia) Pty, Ltd.
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